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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

#### Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

#### Details

Product Status	Obsolete
Core Processor	XC800
Core Size	8-Bit
Speed	27MHz
Connectivity	CANbus, LINbus, SSI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	40
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	3.25K x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	PG-LQFP-64-4
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/xc878clm16ffa5vacxxuma1

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong



#### 8-Bit Single-Chip Microcontroller

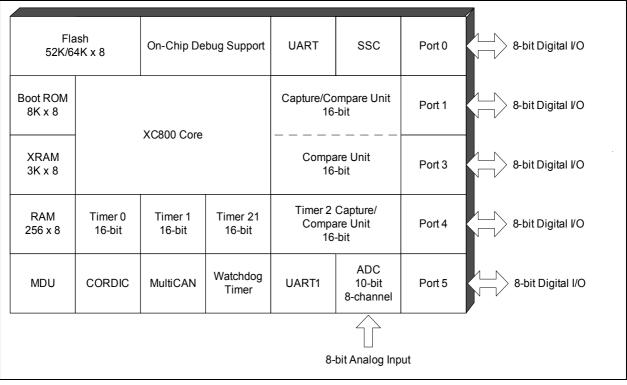
#### XC87xCLM

## **1** Summary of Features

The XC87x has the following features:

- High-performance XC800 Core
  - compatible with standard 8051 processor
  - two clocks per machine cycle architecture (for memory access without wait state)
  - two data pointers
- · On-chip memory
  - 8 Kbytes of Boot ROM
  - 256 bytes of RAM
  - 3 Kbytes of XRAM
  - 64/52 Kbytes of Flash;
    - (includes memory protection strategy)
- I/O port supply at 3.3 V or 5.0 V and core logic supply at 2.5 V (generated by embedded voltage regulator)

(more features on next page)



#### Figure 1 XC87x Functional Units



## XC87xCLM

#### **General Device Information**

#### Table 3Pin Definitions and Functions (cont'd)

Symbol	Pin Number (LQFP-64 / VQFN-48)	Туре	Reset State	Function	
P1.5	39/30		PU	CCPOS0_1 EXINT5_0 T1_1 MRST_2 EXF2_0 RXDO_0	•
P1.6	10/9		PU	CCPOS1_1 T12HR_0 EXINT6_0 RXDC0_2 T21_1	CCU6 Timer 12 Hardware Run Input
P1.7	11/10		PU	CCPOS2_1 T13HR_0 T2_1 TXDC0_2	CCU6 Timer 13 Hardware Run Input Timer 2 Input MultiCAN Node 0 Transmitter Output
					.6 can be used as a software chip t for the SSC.



## XC87xCLM

#### **General Device Information**

#### Table 3Pin Definitions and Functions (cont'd)

Symbol	Pin Number (LQFP-64 / VQFN-48)	Туре	Reset State	Function	
P3.4	51/37		Hi-Z	CC62_0 RXDC0_1 T2EX1_0 T2CC3_1/ EXINT6_3 A14	Input/Output of Capture/Compare channel 2 MultiCAN Node 0 Receiver Input Timer 21 External Trigger Input External Interrupt Input 6/T2CCU Capture/Compare Channel 3 Address Line 14 Output
P3.5	52/38		Hi-Z	COUT62_0 EXF21_0 TXDC0_1 A15	Output of Capture/Compare channel 2 Timer 21 External Flag Output MultiCAN Node 0 Transmitter Output Address Line 15 Output
P3.6	41/32		PU	CTRAP_0	CCU6 Trap Input
P3.7	42/-		Hi-Z	EXINT4_0 COUT63_0 A16	External Interrupt Input 4 Output of Capture/Compare channel 3 Address Line 16 Output



## XC87xCLM

#### **General Device Information**

#### Table 3Pin Definitions and Functions (cont'd)

Symbol	Pin Number (LQFP-64 / VQFN-48)	Туре	Reset State	Function	
P5.5	15/-		PU	CCPOS2_0 CTRAP_1 CC60_3	CCU6 Hall Input 2 CCU6 Trap Input Input of Capture/Compare channel 0
				TDO_1 TXD1_2	JTAG Serial Data Output UART1 Transmit Data Output/ Clock Output
				T2CC0_2/ EXINT3_3 A5	External Interrupt Input 3/T2CCU Capture/Compare Channel 0 Address Line 5 Output
P5.6	19/-		PU	TCK_1 RXDO1_2 T2CC1_2/ EXINT4_3 A6	
P5.7	20/-		PU	TDI_1 RXD1_2 T2CC3_2/ EXINT6_4 A7	JTAG Serial Data Input UART1 Receive Data Input External Interrupt Input 6/T2CCU Capture/Compare Channel 3 Address Line 7 Output



The page register has the following definition:

#### MOD\_PAGE Page Register for module MOD

Reset Value: 00<sub>H</sub>

7	6	5	4	3	2	1	0
0	Ρ	ST	NR	0		PAGE	
v	V	V	V	r		rw	I

Field	Bits	Туре	Description
PAGE	[2:0]	rw	<b>Page Bits</b> When written, the value indicates the new page. When read, the value indicates the currently active page.
STNR	[5:4]	W	Storage NumberThis number indicates which storage bit field is the target of the operation defined by bit field OP.If $OP = 10_B$ , the contents of PAGE are saved in STx before being overwritten with the new value.If $OP = 11_B$ , the contents of PAGE are overwritten by the contents of STx. The value written to the bit positions of PAGE is ignored.00ST0 is selected. 0101ST1 is selected. 1010ST2 is selected. 1111ST3 is selected.



#### Table 12T2CCU Register Overview (cont'd)

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
C5 <sub>H</sub>	T2CCU_CCTH Reset: 00 <sub>H</sub>	Bit Field		Ι	Ι	C	СТ			Ι
	T2CCU Capture/Compare Timer Register High	Туре				rv	vh			
C6 <sub>H</sub>	T2CCU_CCTCON Reset: 00 <sub>H</sub> T2CCU CaptureCcompare	Bit Field		ССТ	PRE		CCTO VF	CCTO VEN	TIMSY N	CCTS T
	Timer Control Register	Туре		r	W		rwh	rw	rw	rw
RMAP =	0, PAGE 2									
C0 <sub>H</sub>	<b>T2CCU_COSHDWReset: 00<sub>H</sub></b> T2CCU Capture/compare Enable Register	Bit Field	ENSH DW	TXOV	COOU T5	COOU T4	COOU T3	COOU T2	COOU T1	COOU T0
		Туре	rwh	rwh	rwh	rwh	rwh	rwh	rwh	rwh
C1 <sub>H</sub>	T2CCU_CC0L Reset: 00 <sub>H</sub> T2CCU Capture/Compare	Bit Field				CC/	/ALL			
	Register 0 Low	Туре				rv	vh			
C2 <sub>H</sub>	T2CCU_CC0H Reset: 00 <sub>H</sub>	Bit Field				CCV	/ALH			
	T2CCU Capture/compare Register 0 High	Туре				rv	vh			
C3 <sub>H</sub>	T2CCU_CC1L Reset: 00 <sub>H</sub>	Bit Field				CC/	/ALL			
	T2CCU Capture/compare Register 1 Low	Туре				rv	vh			
C4 <sub>H</sub>	T2CCU_CC1H Reset: 00 <sub>H</sub>	Bit Field				CCV	/ALH			
	T2CCU Capture/compare Register 1 High	Туре				rv	vh			
C5 <sub>H</sub>	T2CCU_CC2L Reset: 00 <sub>H</sub>	Bit Field	ield CCVALL							
	T2CCU Capture/compare Register 2 Low	Туре				rv	vh			
C6 <sub>H</sub>	T2CCU_CC2H Reset: 00 <sub>H</sub>	Bit Field				CCV	/ALH			
	T2CCU Capture/compare Register 2 High	Туре				rv	vh			
RMAP =	0, PAGE 3									
C0 <sub>H</sub>	T2CCU_COCON Reset: 00 <sub>H</sub> T2CCU Compare Control	Bit Field	CCM5	CCM4	CM5F	CM4F	POLB	POLA	CON	NOD
	Register	Туре	rw	rw	rwh	rwh	rw	rw	r	W
C1 <sub>H</sub>	T2CCU_CC3L Reset: 00 <sub>H</sub>	Bit Field				CC/	/ALL			
	T2CCU Capture/compare Register 3 Low	Туре				rv	vh			
C2 <sub>H</sub>	T2CCU_CC3H Reset: 00 <sub>H</sub>	Bit Field				CCV	/ALH			
	T2CCU Capture/compare Register 3 High	Туре				rv	vh			
C3 <sub>H</sub>	T2CCU_CC4L Reset: 00 <sub>H</sub>	Bit Field				CC/	/ALL			
	T2CCU Capture/compare Register 4 Low	Туре				rv	vh			
C4 <sub>H</sub>	T2CCU_CC4H Reset: 00 <sub>H</sub>	Bit Field	eld CCVALH							
	T2CCU Capture/compare Register 4 High	Туре	rwh							
C5 <sub>H</sub>	T2CCU_CC5L Reset: 00 <sub>H</sub>	Bit Field				CC/	/ALL			
	T2CCU Capture/compare Register 5 Low	Туре				rv	vh			
C6 <sub>H</sub>	T2CCU_CC5H Reset: 00 <sub>H</sub>	Bit Field				CCV	/ALH			
	T2CCU Capture/compare Register 5 High	Туре				rv	vh			



#### Table 14CCU6 Register Overview (cont'd)

Addr	Register Name	Bit	7	6	5	4	3	2	1	0	
FC <sub>H</sub>	CCU6_CC61SRL Reset: 00 <sub>H</sub>	Bit Field				CC6	S1SL	<u> </u>	<u> </u>		
	Capture/Compare Shadow Register for Channel CC61 Low	Туре				rv	vh				
FD <sub>H</sub>	CCU6_CC61SRH Reset: 00 <sub>H</sub>	Bit Field				CC6	1SH				
	Capture/Compare Shadow Register for Channel CC61 High	Туре	rwh								
FE <sub>H</sub>	CCU6_CC62SRL Reset: 00 <sub>H</sub>	Bit Field	CC62SL								
	Capture/Compare Shadow Register for Channel CC62 Low	Туре	rwh								
FF <sub>H</sub>	CCU6_CC62SRH Reset: 00 <sub>H</sub>	Bit Field				CC6	2SH				
	Capture/Compare Shadow Register for Channel CC62 High	Туре				rv	vh				
RMAP =	= 0, PAGE 1										
9A <sub>H</sub>	CCU6_CC63RL Reset: 00 <sub>H</sub>	Bit Field				CC6	3VL				
	Capture/Compare Register for Channel CC63 Low	Туре				r	h				
9в <sub>Н</sub>	CCU6_CC63RH Reset: 00 <sub>H</sub>	Bit Field				CC6	3VH				
	Capture/Compare Register for Channel CC63 High	Туре				r	h				
9CH	CCU6_T12PRL Reset: 00 <sub>H</sub>	Bit Field				T12	PVL				
	Timer T12 Period Register Low	Туре	rwh								
9D <sub>H</sub>	CCU6_T12PRH Reset: 00 <sub>H</sub>	Bit Field				T12	PVH				
	Timer T12 Period Register High	Туре	rwh								
9E <sub>H</sub>	CCU6_T13PRL Reset: 00 <sub>H</sub> Timer T13 Period Register Low	Bit Field				T13	PVL				
		Туре	rwh								
9F <sub>H</sub>	CCU6_T13PRH Reset: 00 <sub>H</sub> Timer T13 Period Register High	Bit Field				T13	PVH				
		Туре				rv	vh				
A4 <sub>H</sub>	CCU6_T12DTCL Reset: 00 <sub>H</sub> Dead-Time Control Register for	Bit Field				D	ΓM				
	Timer T12 Low	Туре				r	N	1	1		
A5 <sub>H</sub>	CCU6_T12DTCH Reset: 00 <sub>H</sub> Dead-Time Control Register for	Bit Field	0	DTR2	DTR1	DTR0	0	DTE2	DTE1	DTE0	
	Timer T12 High	Туре	r	rh	rh	rh	r	rw	rw	rw	
A6 <sub>H</sub>	CCU6_TCTR0L Reset: 00 <sub>H</sub> Timer Control Register 0 Low	Bit Field	СТМ	CDIR	STE1 2	T12R	T12 PRE		T12CLK		
		Туре	rw	rh	rh	rh	rw		rw		
а7 <sub>Н</sub>	CCU6_TCTR0H Reset: 00 <sub>H</sub> Timer Control Register 0 High	Bit Field		0	STE1 3	T13R	T13 PRE		T13CLK		
		Туре		r	rh	rh	rw		rw		
FA <sub>H</sub>	CCU6_CC60RL Reset: 00 <sub>H</sub>	Bit Field				CC6	60VL				
	Capture/Compare Register for Channel CC60 Low	Туре				r	h				
FB <sub>H</sub>	CCU6_CC60RH Reset: 00 <sub>H</sub>	Bit Field				CC6	60VH				
	Capture/Compare Register for Channel CC60 High	Туре				r	h				
FC <sub>H</sub>	CCU6_CC61RL Reset: 00 <sub>H</sub>	Bit Field				CC6	51VL				
	Capture/Compare Register for Channel CC61 Low	Туре				r	h				



## 3.2.4.15 Flash Registers

The Flash SFRs can be accessed in the mapped memory area (RMAP = 1).

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
RMAP =	= 1									
D1 <sub>H</sub>	FCON Reset: 10 <sub>H</sub> P-Flash Control Register	Bit Field	0	FBSY	YE	1	NVST R	MAS1	ERAS E	PROG
		Туре	r	rh	rwh	r	rw	rw	rw	rw
D2 <sub>H</sub>	EECON Reset: 10 <sub>H</sub> D-Flash Control Register	Bit Field	0	EEBS Y	YE	1	NVST R	MAS1	ERAS E	PROG
		Туре	r	rh	rwh	r	rw	rw	rw	rw
D3 <sub>H</sub>	FCS Reset: 80 <sub>H</sub> Flash Control and Status	Bit Field	1	SBEIE	FTEN	0	EEDE RR	EESE RR	FDER R	FSER R
	Register	Туре	r	rw	rwh	r	rwh	rwh	rwh	rwh
D4 <sub>H</sub>	FEAL Reset: 00 <sub>H</sub>	Bit Field	ECCEADDR							
	Flash Error Address Register, Low Byte	Туре	rh							
D5 <sub>H</sub>	FEAH Reset: 00 <sub>H</sub>	Bit Field				ECCE	ADDR			
	Flash Error Address Register, High Byte	Туре				r	h			
D6 <sub>H</sub>	FTVAL Reset: 78 <sub>H</sub>	Bit Field	MODE				OFVAL			
	Flash Timer Value Register	Туре	rw rw							
dd <sub>H</sub>	DD <sub>H</sub> FCS1 Reset: 00 <sub>H</sub> Flash Control and Status					0				EEAB ORT
	Register 1	Туре				r				rwh

#### Table 19Flash Register Overview



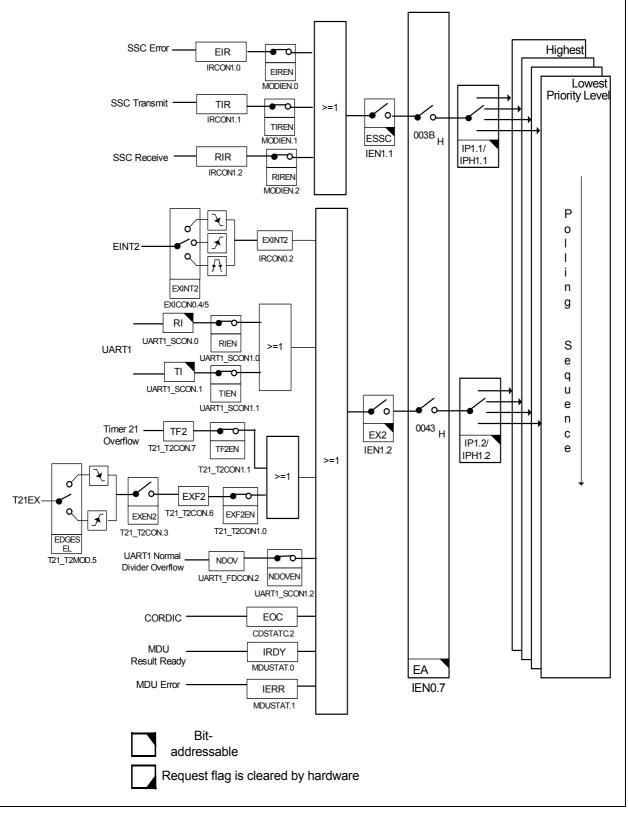


Figure 15 Interrupt Request Sources (Part 3)



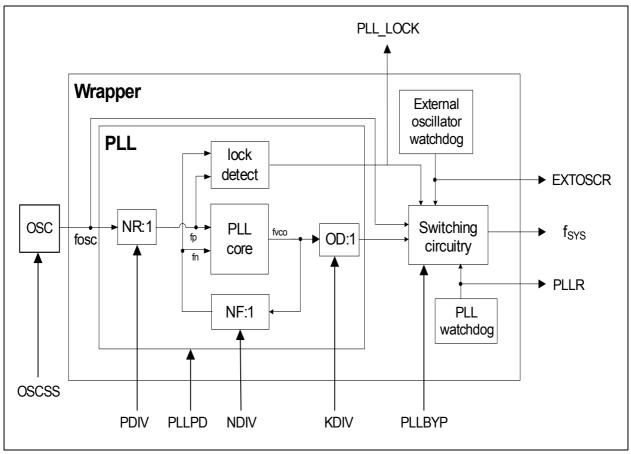


Figure 20 CGU Block Diagram

#### **Direct Drive (PLL Bypass Operation)**

During PLL bypass operation, the system clock has the same frequency as the external clock source.

(3.1)

$$f_{SYS} = f_{OSC}$$

#### PLL Mode

The CPU clock is derived from the oscillator clock, divided by the NR factor (PDIV), multiplied by the NF factor (NDIV), and divided by the OD factor (KDIV). PLL output must



If the WDT is not serviced before the timer overflow, a system malfunction is assumed. As a result, the WDT NMI is triggered (assert FNMIWDT) and the reset prewarning is entered. The prewarning period lasts for  $30_{\rm H}$  count, after which the system is reset (assert WDTRST).

The WDT has a "programmable window boundary" which disallows any refresh during the WDT's count-up. A refresh during this window boundary constitutes an invalid access to the WDT, causing the reset prewarning to be entered but without triggering the WDT NMI. The system will still be reset after the prewarning period is over. The window boundary is from  $0000_{\rm H}$  to the value obtained from the concatenation of WDTWINB and  $00_{\rm H}$ .

After being serviced, the WDT continues counting up from the value ( $\langle WDTREL \rangle * 2^8$ ). The time period for an overflow of the WDT is programmable in two ways:

- The input frequency to the WDT can be selected to be either  $f_{\rm PCLK}/2$  or  $f_{\rm PCLK}/128$
- The reload value WDTREL for the high byte of WDT can be programmed in register WDTREL

The period,  $P_{\rm WDT}$ , between servicing the WDT and the next overflow can be determined by the following formula:

$$P_{WDT} = \frac{2^{(1 + WDTIN \times 6)} \times (2^{16} - WDTREL \times 2^8)}{f_{PCLK}}$$

(3.3)

If the Window-Boundary Refresh feature of the WDT is enabled, the period  $P_{\rm WDT}$  between servicing the WDT and the next overflow is shortened if WDTWINB is greater than WDTREL, see **Figure 25**. This period can be calculated using the same formula by replacing WDTREL with WDTWINB. For this feature to be useful, WDTWINB cannot be smaller than WDTREL.



#### 3.12 CORDIC Coprocessor

The CORDIC Coprocessor provides CPU with hardware support for the solving of circular (trigonometric), linear (multiply-add, divide-add) and hyperbolic functions.

#### Features

- Modes of operation
  - Supports all CORDIC operating modes for solving circular (trigonometric), linear (multiply-add, divide-add) and hyperbolic functions
  - Integrated look-up tables (LUTs) for all operating modes
- Circular vectoring mode: Extended support for values of initial X and Y data up to full range of [-2<sup>15</sup>,(2<sup>15</sup>-1)] for solving angle and magnitude
- Circular rotation mode: Extended support for values of initial Z data up to full range of  $[-2^{15},(2^{15}-1)]$ , representing angles in the range  $[-\pi,((2^{15}-1)/2^{15})\pi]$  for solving trigonometry
- Implementation-dependent operational frequency of up to 80 MHz
- Gated clock input to support disabling of module
- 16-bit accessible data width
  - 24-bit kernel data width plus 2 overflow bits for X and Y each
  - 20-bit kernel data width plus 1 overflow bit for Z
  - With KEEP bit to retain the last value in the kernel register for a new calculation
- 16 iterations per calculation: Approximately 41 clock-cycles or less, from set of start (ST) bit to set of end-of-calculation flag, excluding time taken for write and read access of data bytes.
- Twos complement data processing
- Only exception: X result data with user selectable option for unsigned result
- X and Y data generally accepted as integer or rational number; X and Y must be of the same data form
- Entries of LUTs are 20-bit signed integers
  - Entries of atan and atanh LUTs are integer representations (S19) of angles with the scaling such that  $[-2^{15},(2^{15}-1)]$  represents the range  $[-\pi,((2^{15}-1)/2^{15})\pi]$
  - Accessible Z result data for circular and hyperbolic functions is integer in data form of S15
- Emulated LUT for linear function
  - Data form is 1 integer bit and 15-bit fractional part (1.15)
  - Accessible Z result data for linear function is rational number with fixed data form of S4.11 (signed 4Q16)
- Truncation Error
  - The result of a CORDIC calculation may return an approximation due to truncation of LSBs
  - Good accuracy of the CORDIC calculated result data, especially in circular mode
- Interrupt
  - On completion of a calculation



- CAN functionality according to CAN specification V2.0 B active.
- Dedicated control registers are provided for each CAN node.
- A data transfer rate up to 1 MBaud is supported.
- Flexible and powerful message transfer control and error handling capabilities are implemented.
- Advanced CAN bus bit timing analysis and baud rate detection can be performed for each CAN node via the frame counter.
- Full-CAN functionality: A set of 32 message objects can be individually
  - allocated (assigned) to any CAN node
  - configured as transmit or receive object
  - setup to handle frames with 11-bit or 29-bit identifier
  - counted or assigned a timestamp via a frame counter
  - configured to remote monitoring mode
- Advanced Acceptance Filtering:
  - Each message object provides an individual acceptance mask to filter incoming frames.
  - A message object can be configured to accept only standard or only extended frames or to accept both standard and extended frames.
  - Message objects can be grouped into 4 priority classes.
  - The selection of the message to be transmitted first can be performed on the basis of frame identifier, IDE bit and RTR bit according to CAN arbitration rules.
- Advanced Message Object Functionality:
  - Message Objects can be combined to build FIFO message buffers of arbitrary size, which is only limited by the total number of message objects.
  - Message objects can be linked to form a gateway to automatically transfer frames between 2 different CAN buses. A single gateway can link any two CAN nodes. An arbitrary number of gateways may be defined.
- Advanced Data Management:
  - The Message objects are organized in double chained lists.
  - List reorganizations may be performed any time, even during full operation of the CAN nodes.
  - A powerful, command driven list controller manages the organization of the list structure and ensures consistency of the list.
  - Message FIFOs are based on the list structure and can easily be scaled in size during CAN operation.
  - Static Allocation Commands offer compatibility with TwinCAN applications, which are not list based.
- Advanced Interrupt Handling:
  - Up to 8 interrupt output lines are available. Most interrupt requests can be individually routed to one of the 8 interrupt output lines.
  - Message postprocessing notifications can be flexibly aggregated into a dedicated register field of 64 notification bits.



#### 3.24 Chip Identification Number

The XC87x identity (ID) register is located at Page 1 of address  $B3_{H}$ . The value of ID register is  $49_{H}$ . However, for easy identification of product variants, the Chip Identification Number, which is an unique number assigned to each product variant, is available. The differentiation is based on the product, variant type and device step information.

Two methods are provided to read a device's chip identification number:

- In-application subroutine, GET\_CHIP\_INFO
- Bootstrap loader (BSL) mode A

Table 37 lists the chip identification numbers of available XC87x Flash device variants.

Product Variant	Chip Identification Number
	AC-step
Flash Devices	
XC878-16FF 5V	4B580063 <sub>H</sub>
XC878M-16FF 5V	4B580023 <sub>H</sub>
XC878CM-16FF 5V	4B580003 <sub>H</sub>
XC878LM-16FF 5V	4B500023 <sub>H</sub>
XC878CLM-16FF 5V	4B500003 <sub>H</sub>
XC878-13FF 5V	4B590463 <sub>H</sub>
XC878M-13FF 5V	4B590423 <sub>H</sub>
XC878CM-13FF 5V	4B590403 <sub>H</sub>
XC878LM-13FF 5V	4B510423 <sub>H</sub>
XC878CLM-13FF 5V	4B510403 <sub>H</sub>
XC878-16FF 3V3	4B180063 <sub>H</sub>
XC878M-16FF 3V3	4B180023 <sub>H</sub>
XC878CM-16FF 3V3	4B180003 <sub>H</sub>
XC878-13FF 3V3	4B190463 <sub>H</sub>
XC878M-13FF 3V3	4B190423 <sub>H</sub>
XC878CM-13FF 3V3	4B190403 <sub>H</sub>
XC874CM-16FV 5V	4B580002 <sub>H</sub>
XC874LM-16FV 5V	4B500022 <sub>H</sub>
XC874-16FV 5V	4B580062 <sub>H</sub>

 Table 37
 Chip Identification Number



#### **Electrical Parameters**

#### 4.2.3 ADC Characteristics

The values in the table below are given for an analog power supply between 4.5 V to 5.5 V. The ADC can be used with an analog power supply down to 3 V. But in this case, the analog parameters may show a reduced performance. All ground pins ( $V_{\rm SS}$ ) must be externally connected to one single star point in the system. The voltage difference between the ground pins must not exceed 200mV.

Parameter	Symbol		Lir	nit Val	ues	Unit	Test Conditions/	
			min.	typ.	max.		Remarks	
Analog reference voltage	V <sub>AREF</sub>	SR	V <sub>AGND</sub> + 1	V <sub>DDP</sub>	V <sub>DDP</sub> + 0.05	V	1)	
Analog reference ground	V <sub>AGND</sub>	SR	V <sub>SS</sub> - 0.05	V <sub>SS</sub>	V <sub>AREF</sub> - 1	V	1)	
Analog input voltage range	$V_{AIN}$	SR	$V_{AGND}$	-	V <sub>AREF</sub>	V		
ADC clocks	$f_{\rm ADC}$		-	24	-	MHz	module clock <sup>1)</sup>	
	f <sub>adci</sub>		_	-	14 <sup>2)</sup>	MHz	internal analog clock <sup>1)</sup> See <b>Figure 31</b>	
Sample time	t <sub>S</sub>	CC	(2 + IN <i>t</i> <sub>ADCI</sub>	PCR0.	STC) ×	μS	1)	
Conversion time	t <sub>C</sub>	CC	See S	ection	4.2.3.1	μs	1)	
Differential Nonlinearity	EA <sub>DNL</sub>	CC	-	-	1.5	LSB	10-bit conversion	
Integral Nonlinearity	EA <sub>INL</sub>	CC	-	-	2	LSB	10-bit conversion	
Offset	$ EA_{OFF} $	CC	-	_	3	LSB	10-bit conversion	
Gain	$ EA_{GAIN} $	CC	-	-	2.5	LSB	10-bit conversion	
Switched capacitance at the reference voltage input	C <sub>AREFSW</sub>	CC	_	10	14	pF	1)3)	
Switched capacitance at the analog voltage inputs	C <sub>AINSW</sub>	CC	_	4	5	pF	1)4)	

#### Table 42ADC Characteristics (Operating Conditions apply; $V_{DDP}$ = 5V Range)



#### **Electrical Parameters**

# Table 45Power Supply Current Parameters<sup>1)</sup> (Operating Conditions apply; $V_{\text{DDP}} = 3.3V$ range)

Parameter	Symbol	Limit	Values	Unit	Test	
		typ. <sup>2)</sup>	p. <sup>2)</sup> max. <sup>3)</sup>		Conditions	
$V_{\text{DDP}}$ = 3.3V Range						
Active Mode	I <sub>DDP</sub>	35.4	43	mA	4)	
Idle Mode	I <sub>DDP</sub>	27.6	33	mA	5)	
Active Mode with slow-down enabled	I <sub>DDP</sub>	8.6	13	mA	6)	
Idle Mode with slow-down enabled	I <sub>DDP</sub>	8	12	mA	7)	

1) The table is only applicable to SAF and SAX variants.

2) The typical  $I_{\text{DDP}}$  values are based on preliminary measurements and are to be used as reference only. These values are periodically measured at  $T_{\text{A}}$  = + 25 °C and  $V_{\text{DDP}}$  = 3.3 V.

3) The maximum  $I_{\text{DDP}}$  values are measured under worst case conditions ( $T_{\text{A}}$  = + 105 °C and  $V_{\text{DDP}}$  = 3.6 V).

4)  $I_{\text{DDP}}$  (active mode) is measured with: CPU clock and input clock to all peripherals running at 24 MHz with onchip oscillator of 4 MHz, RESET =  $V_{\text{DDP}}$ ; all other pins are disconnected, no load on ports.

5)  $I_{\text{DDP}}$  (idle mode) is measured with: CPU clock disabled, watchdog timer disabled, input clock to all peripherals enabled and running at 24 MHz, RESET =  $V_{\text{DDP}}$ ; all other pins are disconnected, no load on ports.

- 6)  $I_{\text{DDP}}$  (active mode with slow-down mode) is measured with: CPU clock and input clock to all peripherals running at 1 MHz by setting CLKREL in CMCON to  $1000_{\text{B}}$ ,  $\overline{\text{RESET}} = V_{\text{DDP}}$ ; all other pins are disconnected, no load on ports.
- 7)  $I_{\text{DDP}}$  (idle mode with slow-down mode) is measured with: CPU clock disabled, watchdog timer disabled, input clock to all peripherals enabled and running at 1 MHz by setting CLKREL in CMCON to  $1000_{\text{B}}$ , RESET =  $V_{\text{DDP}}$ ; all other pins are disconnected, no load on ports.



#### **Electrical Parameters**

#### 4.3.2 Output Rise/Fall Times

 Table 47 provides the characteristics of the output rise/fall times in the XC87x.

#### Table 47 Output Rise/Fall Times Parameters (Operating Conditions apply)

-				• •	
Parameter	Symbol	Limit Values		Unit	Test Conditions
		min.	max.		
$V_{\rm DDP}$ = 5V Range				•	
Rise/fall times	t <sub>R</sub> , t <sub>F</sub>	-	10	ns	20 pF. <sup>1) 2)3)</sup>
$V_{\text{DDP}}$ = 3.3V Range					·
Rise/fall times	t <sub>R</sub> , t <sub>F</sub>	-	10	ns	20 pF. <sup>1) 2)4)</sup>
		1 400/	000/ 5		

1) Rise/Fall time measurements are taken with 10% - 90% of pad supply.

2) Not all parameters are 100% tested, but are verified by design/characterization and test correlation.

3) Additional rise/fall time valid for  $C_{\rm L}$  = 20pF - 100pF @ 0.125 ns/pF.

4) Additional rise/fall time valid for  $C_{\rm L}$  = 20pF - 100pF @ 0.225 ns/pF.

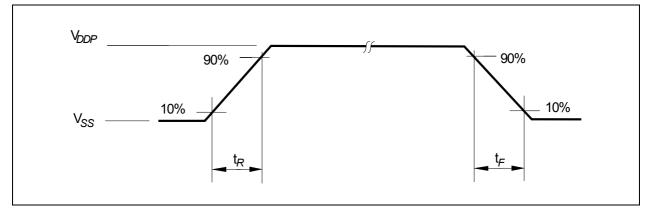


Figure 39 Rise/Fall Times Parameters



#### Package and Quality Declaration

# 5 Package and Quality Declaration

Chapter 5 provides the information of the XC87x package and reliability section.

#### 5.1 Package Parameters

Table 56 provides the thermal characteristics of the package used in XC878 and XC874.

Parameter	Symbol		Lim	nit Values	Unit	Notes
			Min. Max.			
PG-LQFP-64-4 (XC878)	1					
Thermal resistance junction case <sup>1)</sup>	R <sub>TJC</sub> C	CC -		13.8	K/W	-
Thermal resistance junction lead <sup>1)</sup>	$R_{\rm TJL}$ C	CC -		34.6	K/W	-
PG-VQFN-48-22 (XC874)		ľ				
Thermal resistance junction case <sup>1)</sup>	R <sub>TJC</sub> C	CC -		16.6	K/W	-
Thermal resistance junction lead <sup>1)</sup>	R <sub>TJL</sub> C	CC -		30.7	K/W	-

#### Table 56 Thermal Characteristics of the Packages

1) The thermal resistances between the case and the ambient  $(R_{TCA})$ , the lead and the ambient  $(R_{TLA})$  are to be combined with the thermal resistances between the junction and the case  $(R_{TJC})$ , the junction and the lead  $(R_{TJL})$  given above, in order to calculate the total thermal resistance between the junction and the ambient  $(R_{TJA})$ . The thermal resistances between the case and the ambient  $(R_{TCA})$ , the lead and the ambient  $(R_{TLA})$ . The thermal resistances between the case and the ambient  $(R_{TCA})$ , the lead and the ambient  $(R_{TLA})$  depend on the external system (PCB, case) characteristics, and are under user responsibility.

The junction temperature can be calculated using the following equation:  $T_J = T_A + R_{TJA} \times P_D$ , where the  $R_{TJA}$  is the total thermal resistance between the junction and the ambient. This total junction ambient resistance  $R_{TJA}$  can be obtained from the upper four partial thermal resistances, by

a) simply adding only the two thermal resistances (junction lead and lead ambient), or

b) by taking all four resistances into account, depending on the precision needed.



#### Package and Quality Declaration



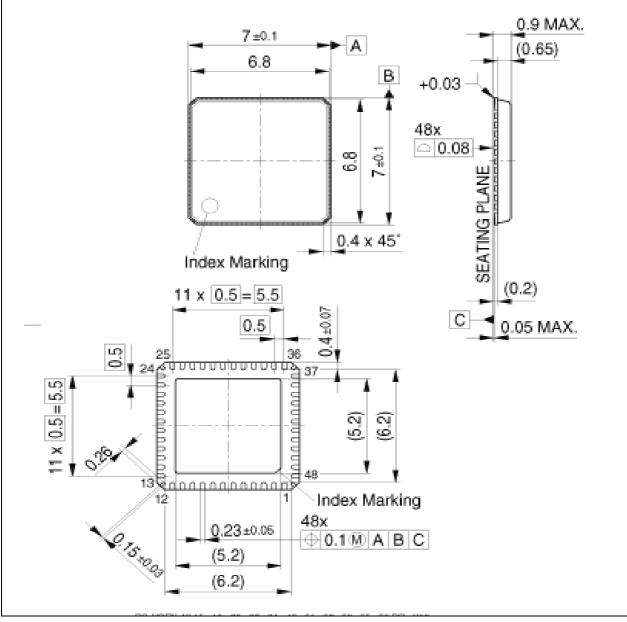


Figure 48 PG-VQFN-48-22 Package Outline

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